
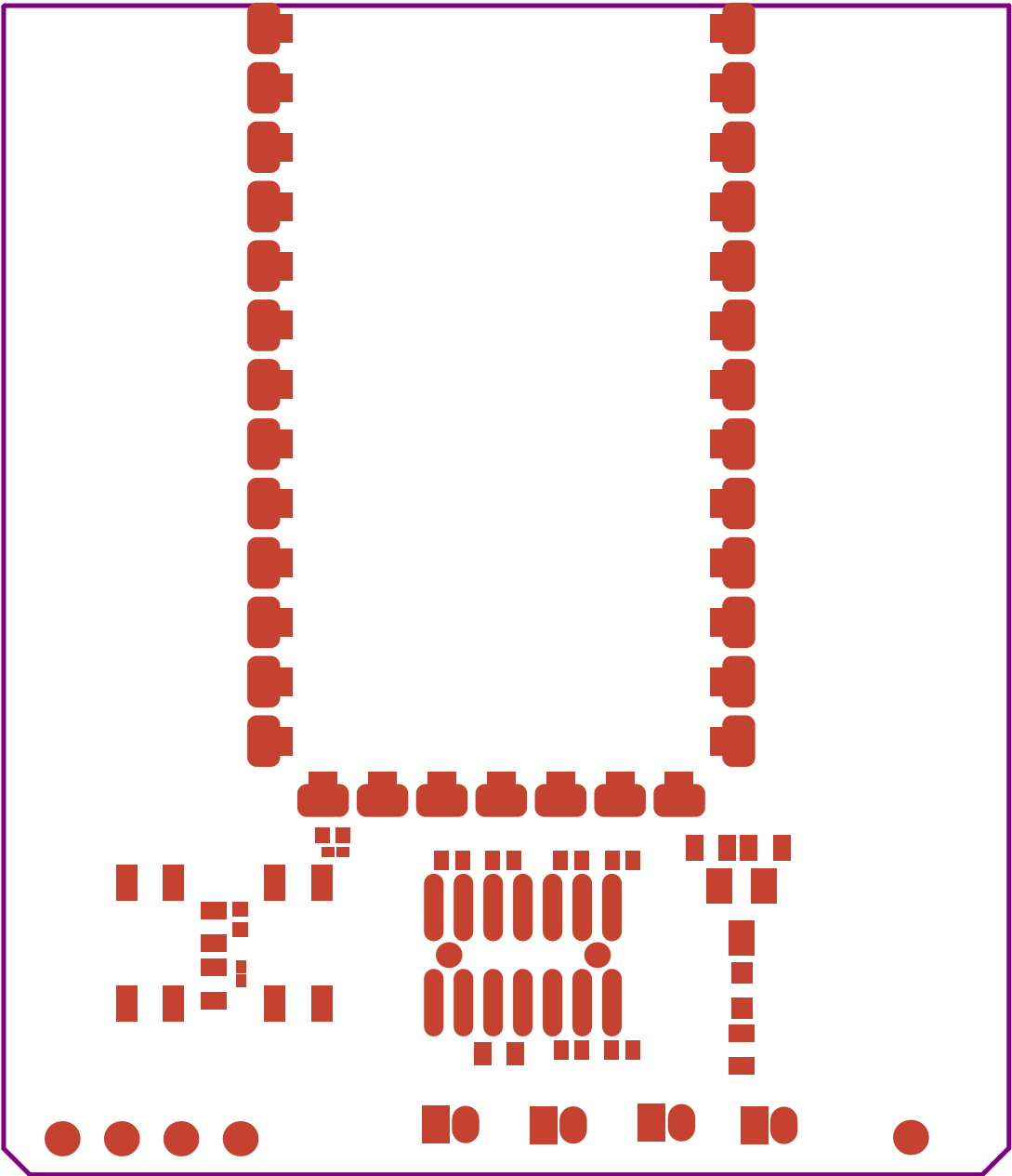

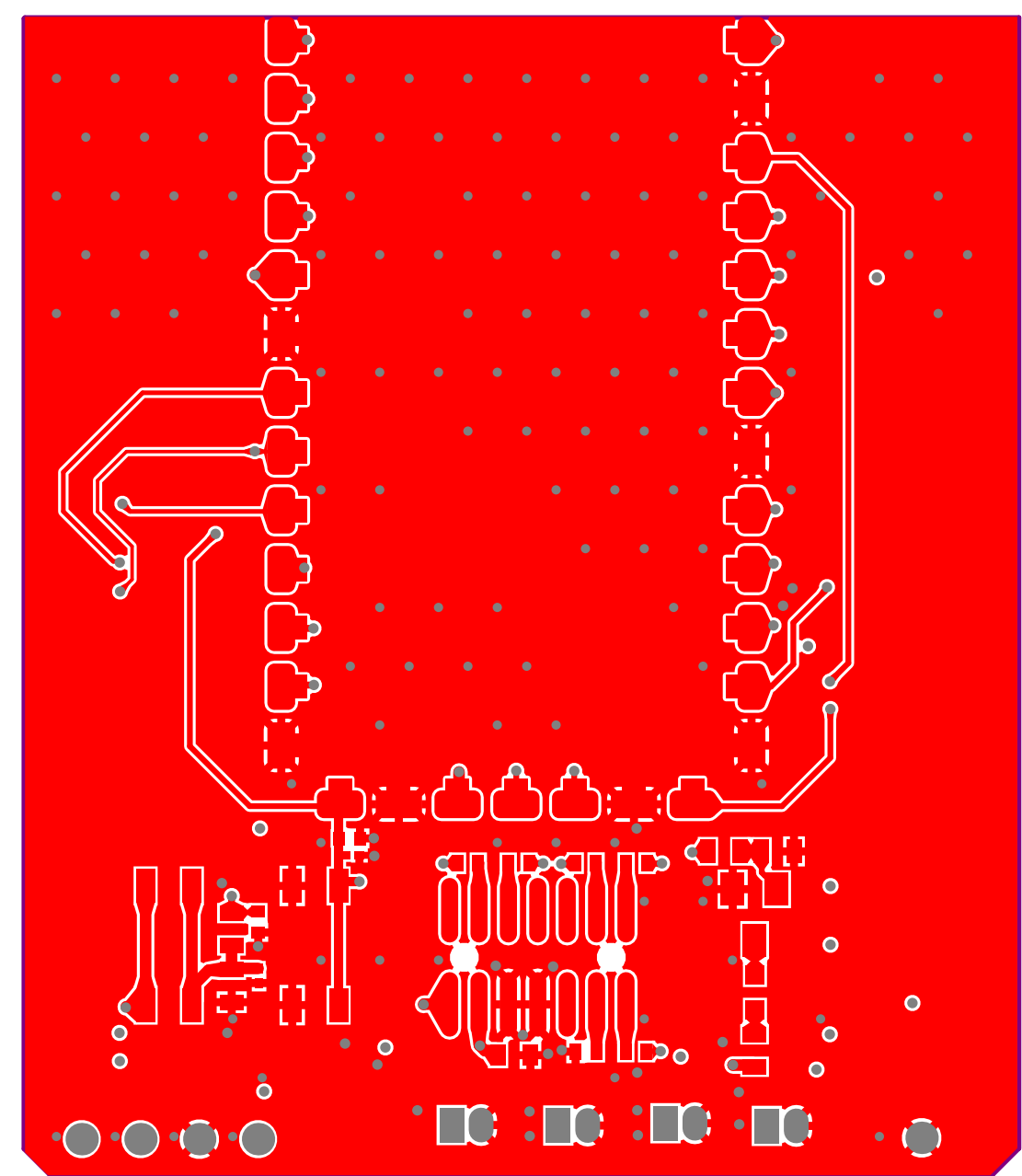



Project: STM32WW611MNA6B+STM32U575AII6		<div>Stamp Ref Board</div> 
Layer: <b>Top Overlay</b>	Gerber: <b>.GTO</b>	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	

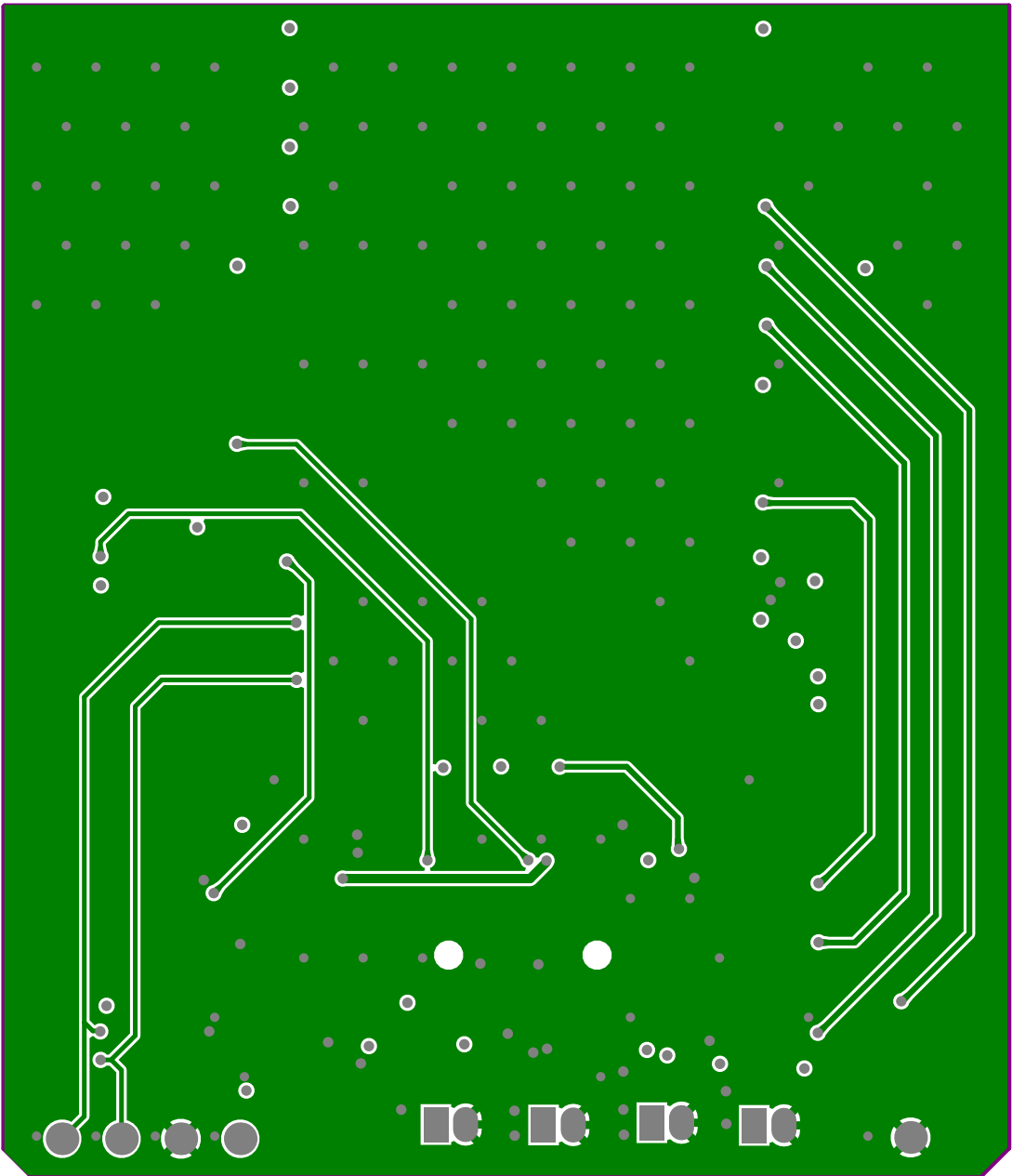



Project: STM32WW611MNA6B+STM32U575All6		
Layer: <b>Top Solder</b>	Gerber: <b>.GTS</b>	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	

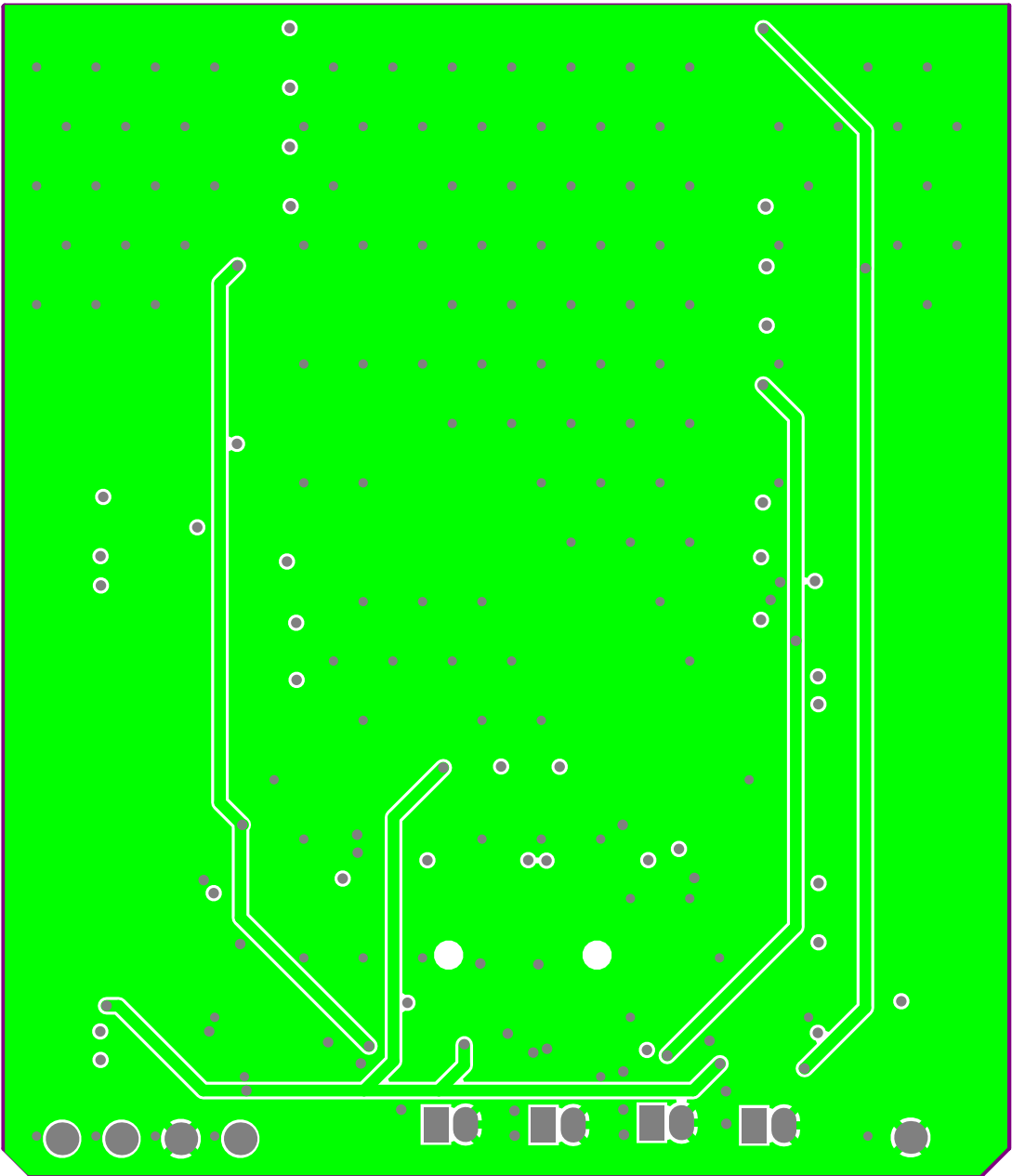
Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0.70mil	3.2
1	Top Layer		1.60mil	
	Dielectric 1	FR-4	3.00mil	3.7
2	Internal 1		1.20mil	
	Dielectric 3		50.00mil	4.5
3	Internal 2		1.20mil	
	Dielectric 2		3.00mil	3.7
4	Bottom Layer		1.60mil	
	Bottom Solder	Solder Resist	0.70mil	4.2
	Bottom Overlay			




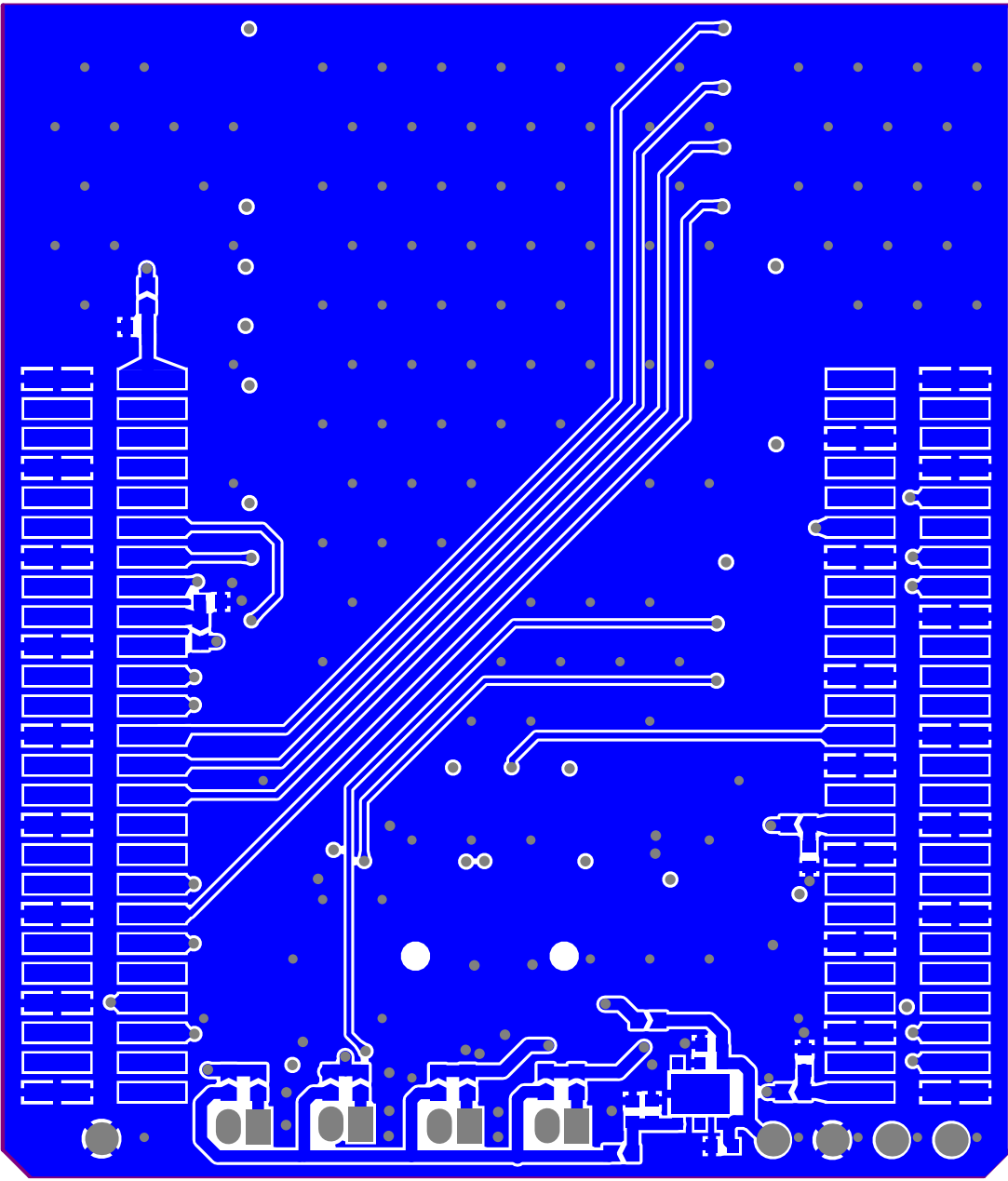
Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> <div></div>
Layer: <b>Top Layer</b>	Gerber: <b>.GTL</b>	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	




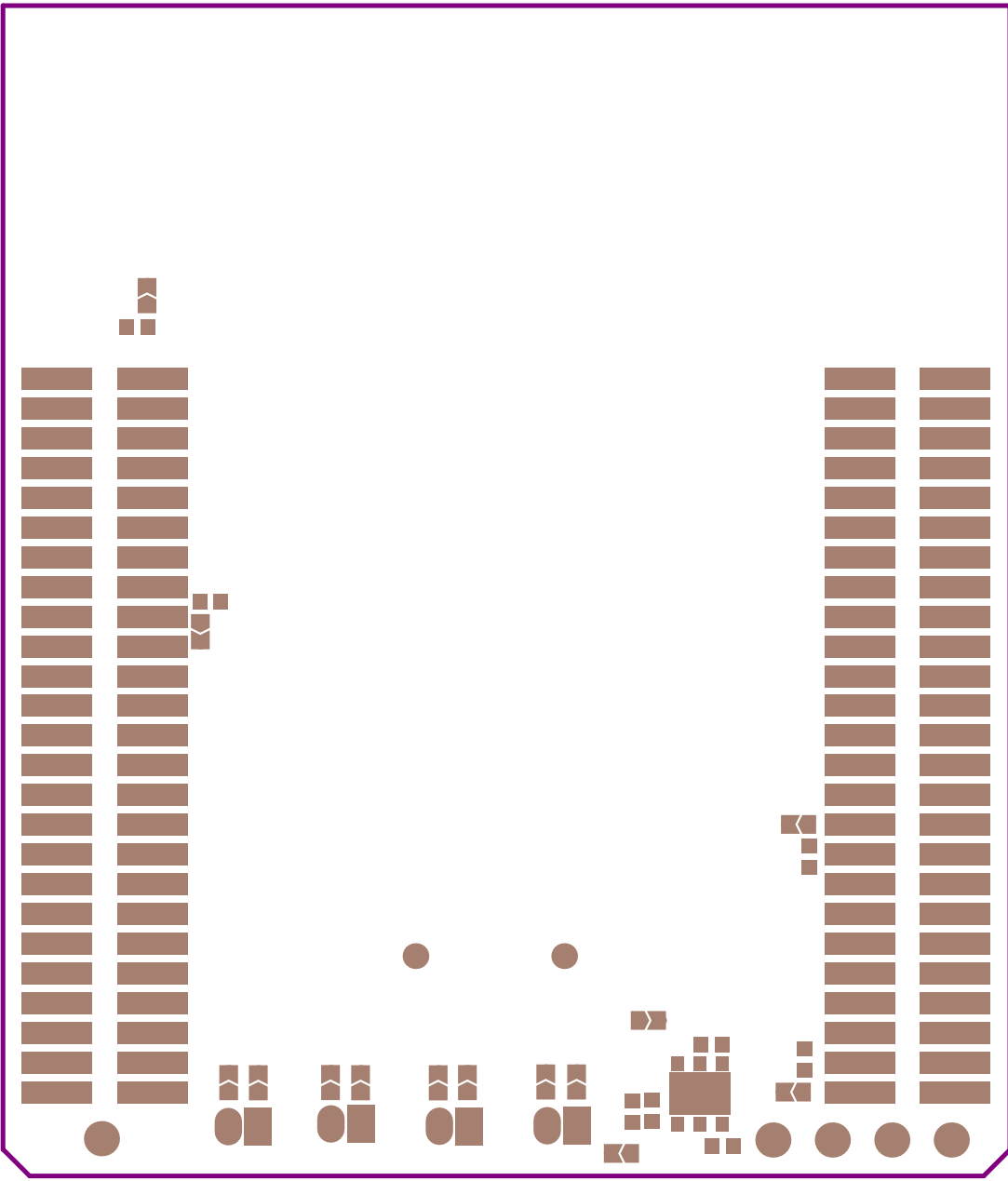
Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> 
Layer: Internal 1	Gerber: .G1	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	




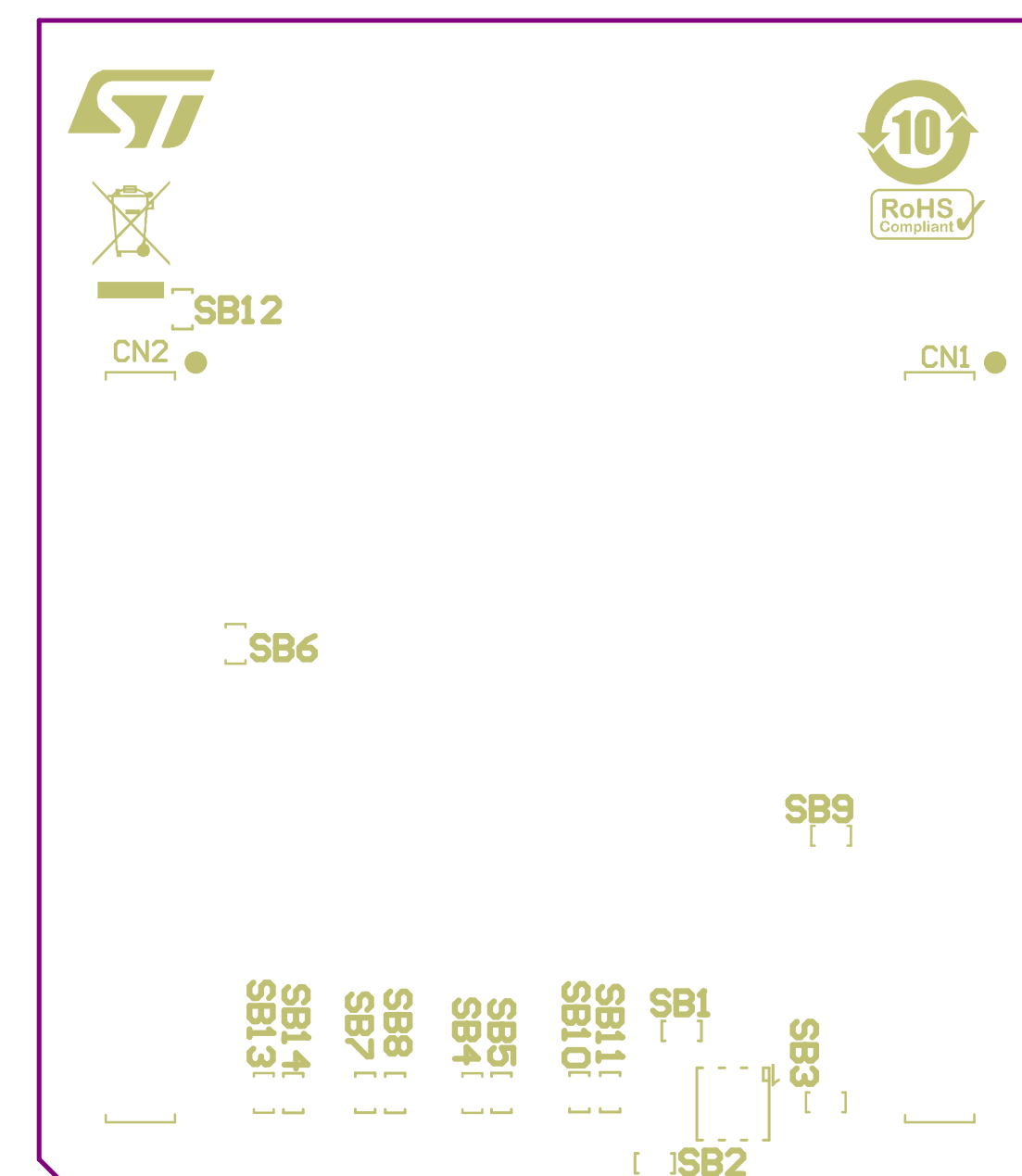
Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> 
Layer: Internal 2	Gerber: .G2	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	




Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> <div></div>
Layer: <a href="#">Bottom Layer</a>	Gerber: <a href="#">.GBL</a>	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	



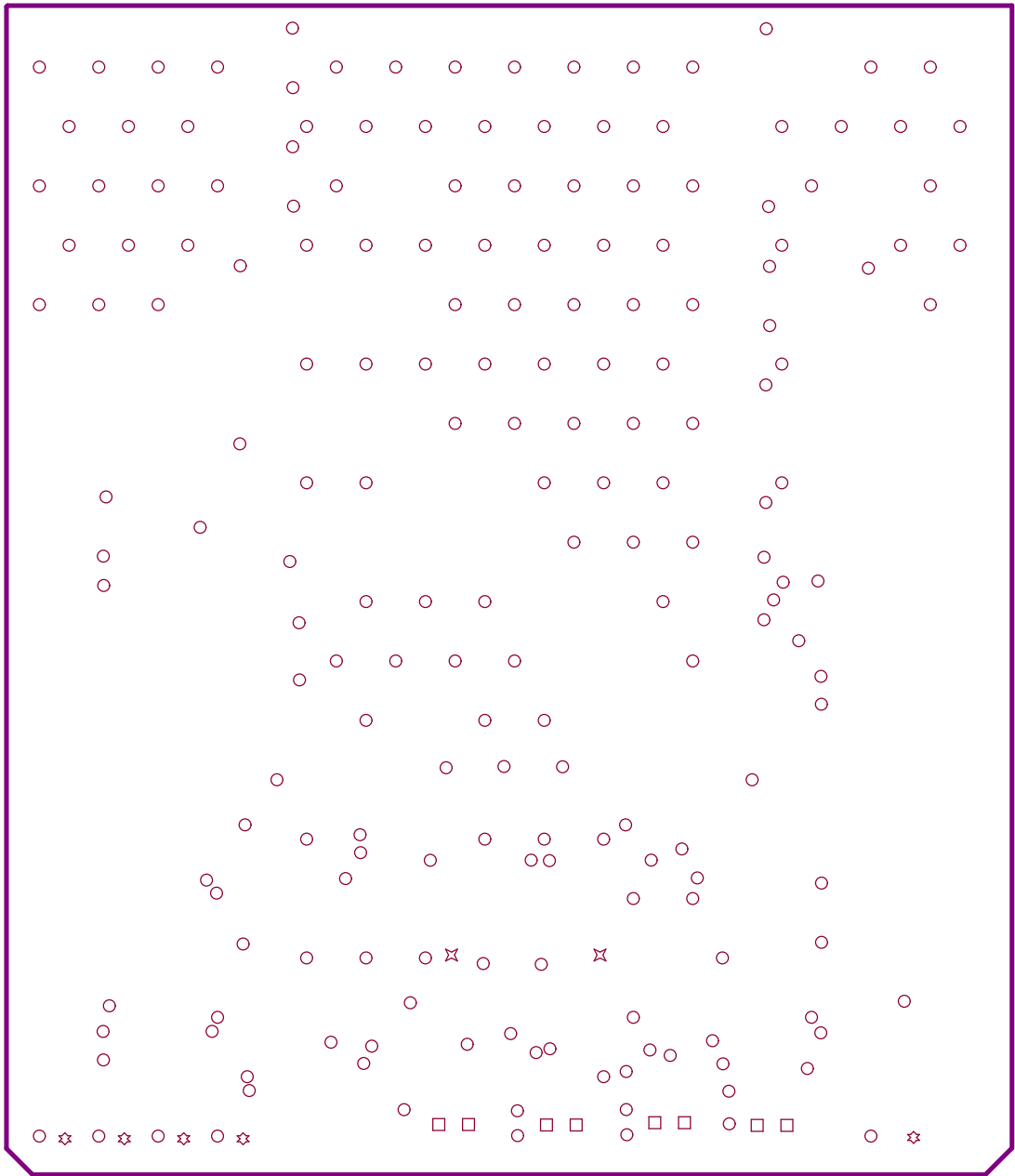
Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> <div></div>
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	



Project: STM32WW611MNA6B+STM32U575All6		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
✕	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m105p0				-	-
✧	5	1.00mm (39.37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c140h100m145				-	-
□	8	0.80mm (31.50mil)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
○	194	0.20mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
	209 Total												



PCB SPECIFICATIONS :

- A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140
- B. MATERIAL FAMILY :

N/A
- C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK
- D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK
- E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER
- F. IMPEDANCE CONTROL :


☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Project: STM32WW611MNA6B+STM32U575All6		<div>Stamp Ref Board</div> <div></div>
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: B2416	
Date: December 2024	Rev: A	